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(12) **United States Design Patent**
Yu et al.

(10) **Patent No.:** **US D616,769 S**
(45) **Date of Patent:** **** Jun. 1, 2010**

(54) **RADIATION DETECTING DEVICE CARD**

(57) **CLAIM**

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The ornamental design for a radiation detecting device card, as shown and described.

(73) Assignee: **Hitachi Cable, Ltd.**, Tokyo (JP)

DESCRIPTION

(**) Term: **14 Years**

FIG. 1 is an enlarged top, front and right side perspective view of a radiation detecting device card showing our new design;

(21) Appl. No.: **29/311,843**

FIG. 2 is a front view thereof;

(22) Filed: **Jul. 8, 2009**

FIG. 3 is a back view thereof;

(30) **Foreign Application Priority Data**

FIG. 4 is a left side view thereof;

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FIG. 5 is a top view thereof;

(51) **LOC (9) Cl.** **10-04**

FIG. 6 is a bottom view thereof; and,

(52) **U.S. Cl.** **D10/47**

FIG. 7 is an enlarged top, front and right side perspective view of the radiation detecting device card in a usage condition;

(58) **Field of Classification Search** D10/47;
250/370.01, 370.07, 370 P, 473.1, 474.1,
250/484.3-484.5; 356/319, 328

In FIG. 7, an arrow indicates an incident direction of radiation.

See application file for complete search history.

This article is a radiation detecting device card, to be inserted in a radiation detecting device for detecting a radiation. The radiation detecting device card comprises a substrate, a plurality of semiconductor elements fixed on both sides of the substrate, each the semiconductor elements detecting the radiation, a pair of flexible substrates provided to the semiconductor elements at an opposite side to the substrate, and a pair of card holders holding the substrate at a region adjacent to the semiconductor elements by sandwiching the substrate. The radiation detecting device card further comprises a metal plate member at ends of the card holder. The radiation is incident to an end face of the semiconductor element.

(56) **References Cited**

U.S. PATENT DOCUMENTS

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The broken line showing of the arrow indication is included for the purpose of illustrating non-claimed subject matter and forms no part of the claimed design.

* cited by examiner

Primary Examiner—Antoine D Davis

(74) *Attorney, Agent, or Firm*—McGinn IP Law Group, PLLC

1 Claim, 7 Drawing Sheets

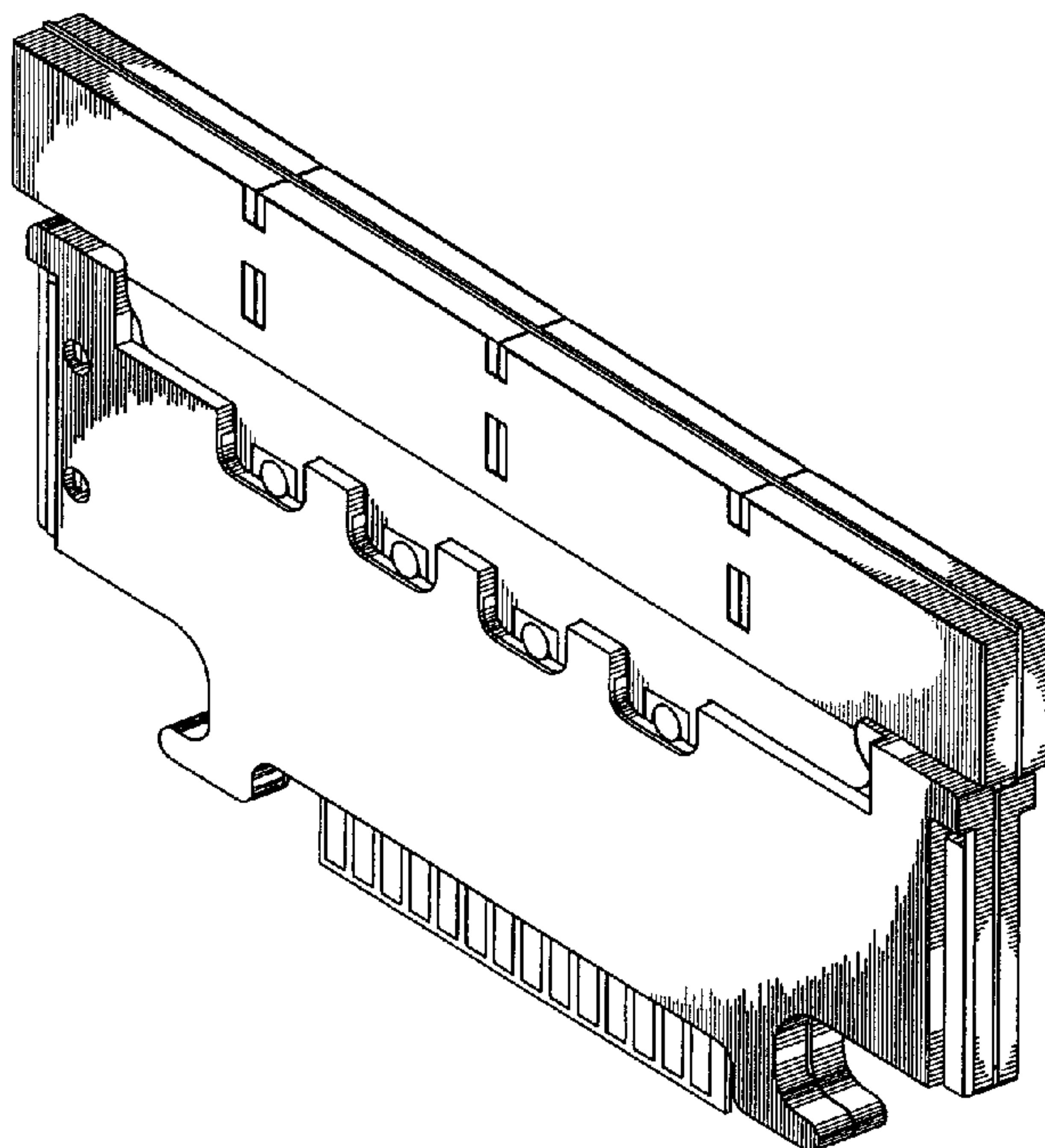


FIG. 1

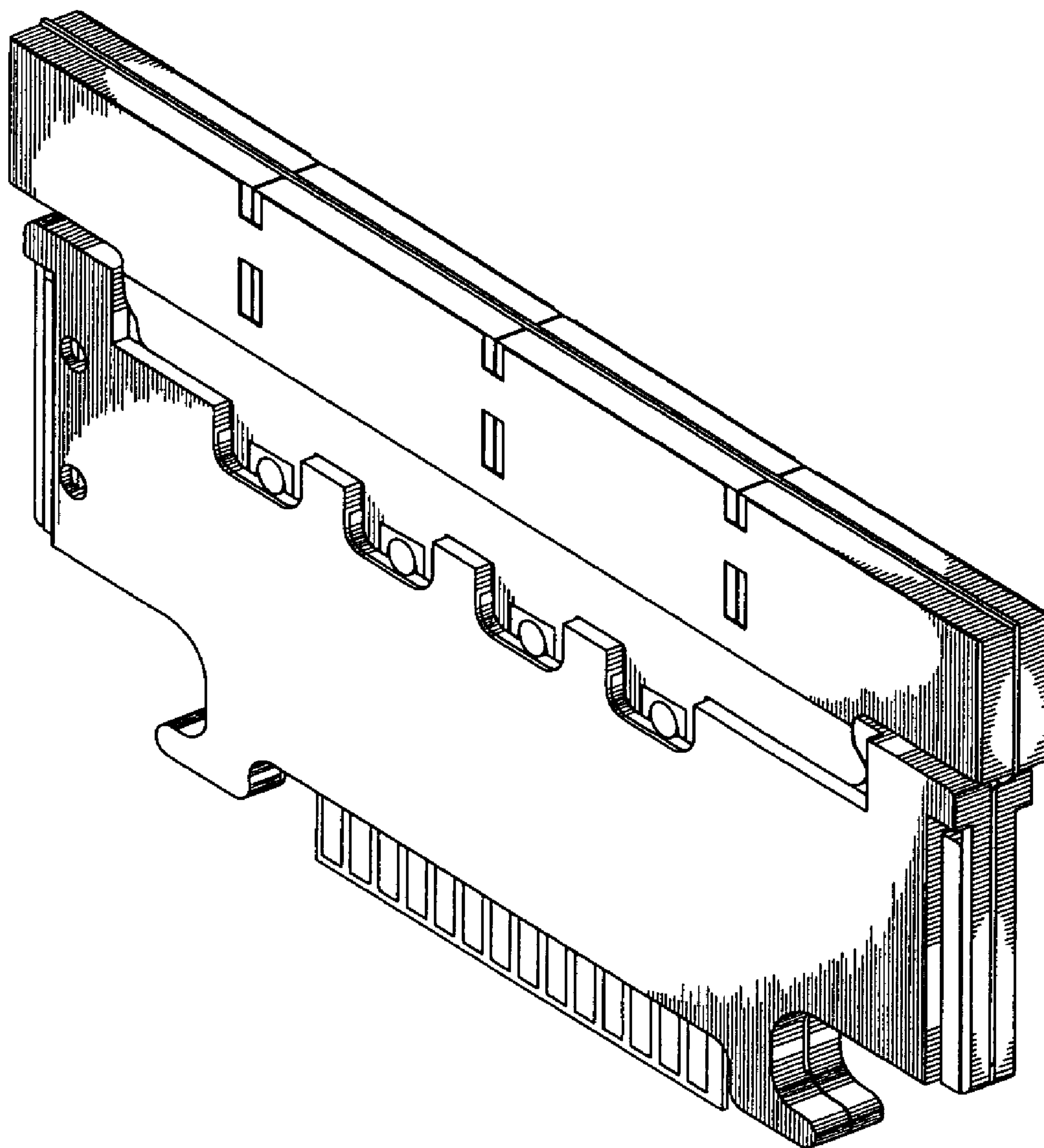


FIG.2

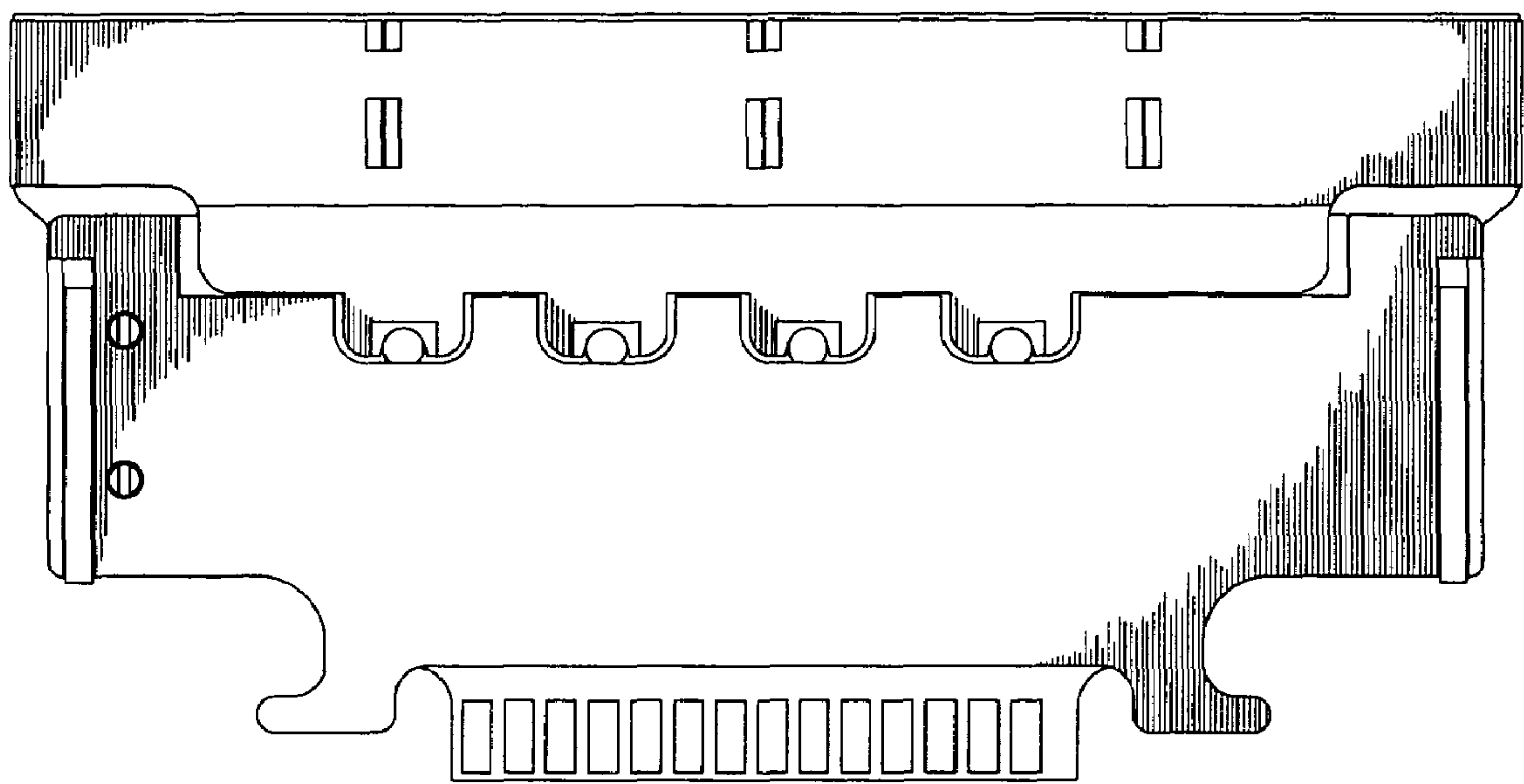


FIG.3

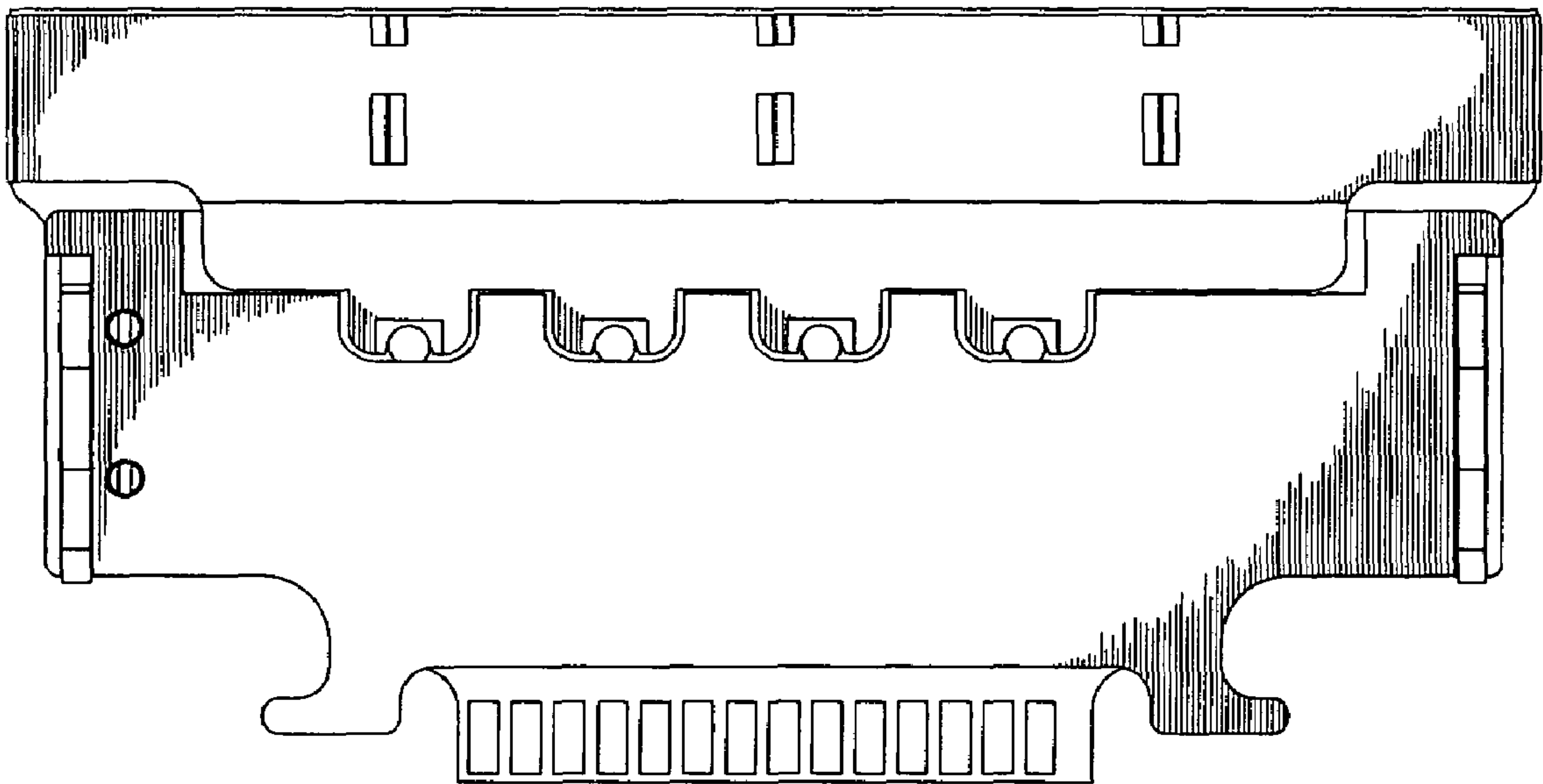


FIG. 4

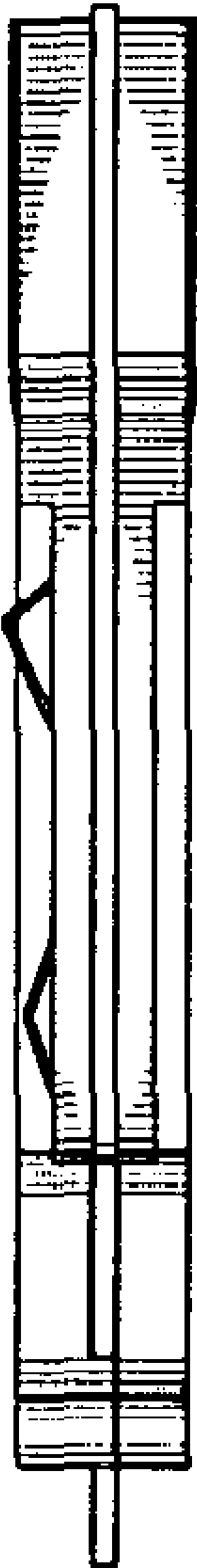


FIG.5



FIG.6

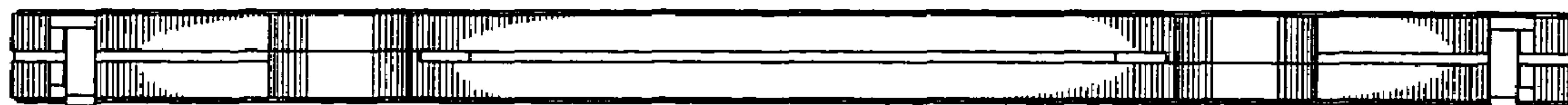


FIG.7

